

DOCKET NO: 251598US0



IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF

:

YUKIO HOSAKA, ET AL.

: EXAMINER: RACHUBA, MAURINA T.

SERIAL NO: 10/820,123

:

FILED: APRIL 8, 2004

: GROUP ART UNIT: 3723

FOR: ABRASIVE PAD, METHOD AND
METAL MOLD FOR MANUFACTURING
THE SAME, AND SEMICONDUCTOR
WAFER POLISHING METHOD

:

AMENDMENT AND REQUEST FOR RECONSIDERATION

COMMISSIONER FOR PATENTS
ALEXANDRIA, VIRGINIA 22313

SIR:

In response to the Office Action dated June 7, 2006, Applicants request reconsideration of the above-identified application in view of the following amendments and remarks:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Support for the Amendment begins on page 6 of this paper.

Request for Reconsideration begins on page 7 of this paper.